



HTIP107

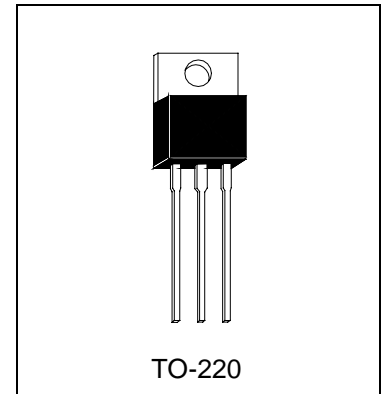
PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HTIP107 is designed for use in general purpose amplifier and low-speed switching applications.

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 - Total Power Dissipation (Tc=25°C) 80 W
 - Total Power Dissipation (Ta=25°C) 2 W
- Maximum Voltages and Currents
 - BVCBO Collector to Base Voltage -100 V
 - BVCEO Collector to Emitter Voltage -100 V
 - BVEBO Emitter to Base Voltage -5 V
 - IC Collector Current -8 A

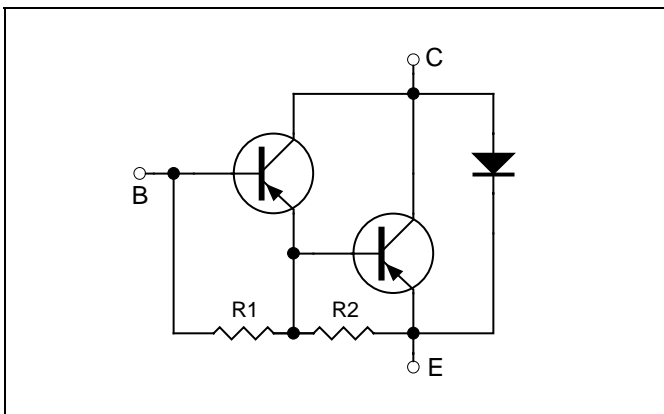


Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-100	-	-	V	IC=-1mA, IE=0
BVCEO	-100	-	-	V	IC=-30mA, IB=0
ICBO	-	-	-50	uA	VCB=-100V, IE=0
ICEO	-	-	-50	uA	VCE=-50V, IB=0
IEBO	-	-	-8	mA	VEB=-5V, IC=0
*VCE(sat)1	-	-	-2	V	IC=-3A, IB=-6mA
*VCE(sat)2	-	-	-2.5	V	IC=-8A, IB=-80mA
*VBE(on)	-	-	-2.8	V	IC=-8A, VCE=-4V
*hFE1	1	-	20	K	IC=-3A, VCE=-4V
*hFE2	200	-	-		IC=-8A, VCE=-4V
Cob	-	-	300	pF	VCB=-10V, f=0.1MHz

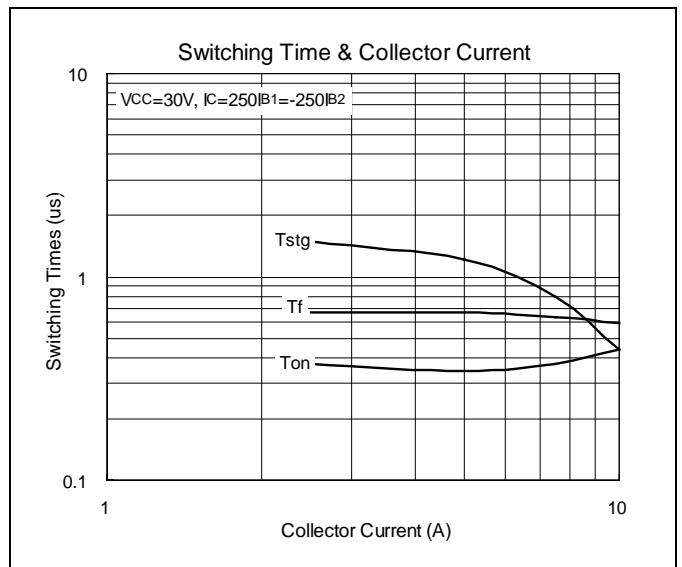
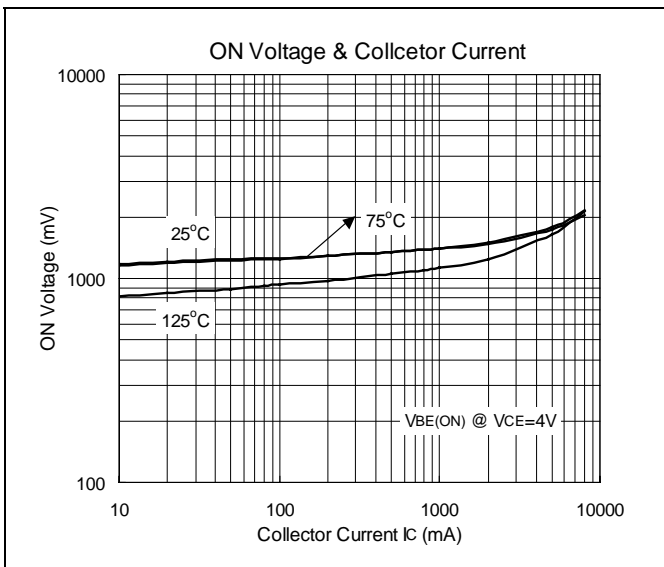
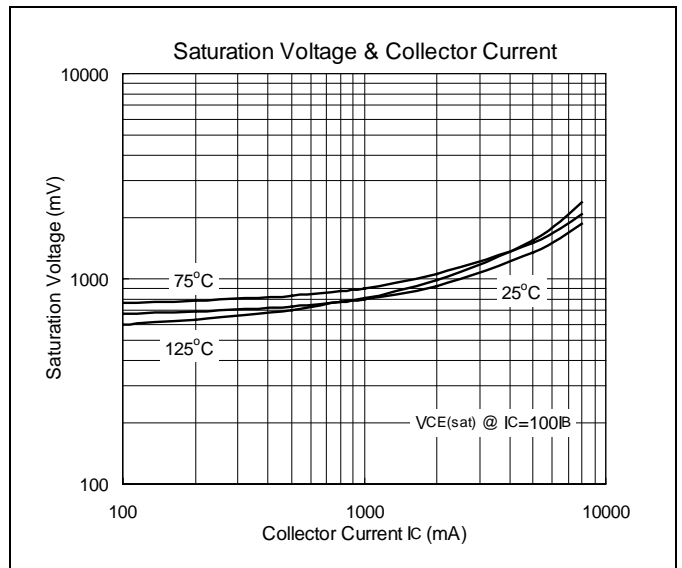
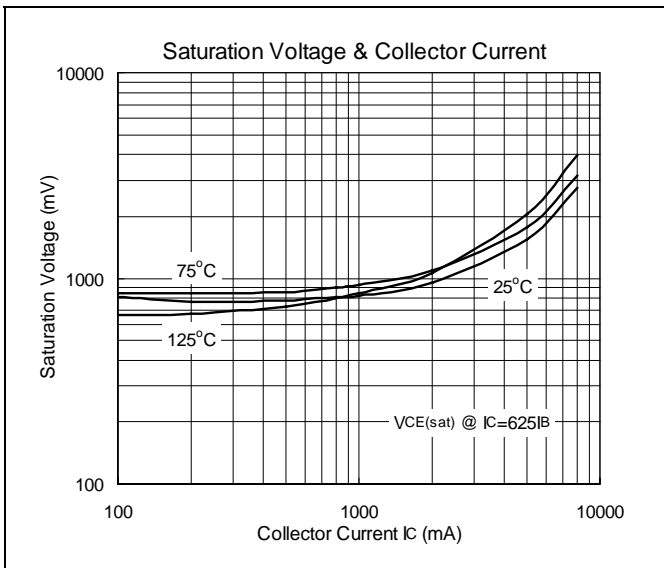
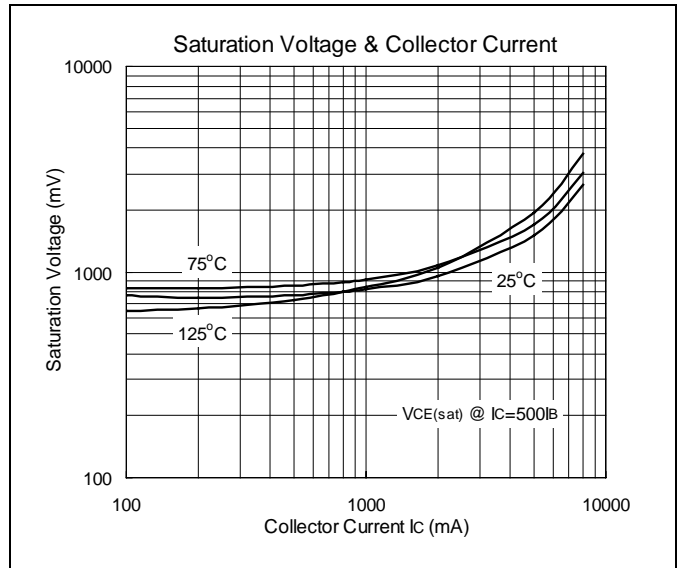
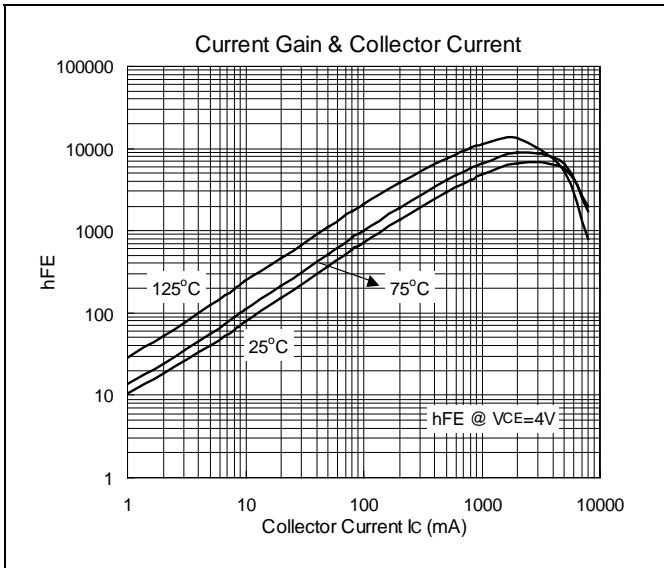
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

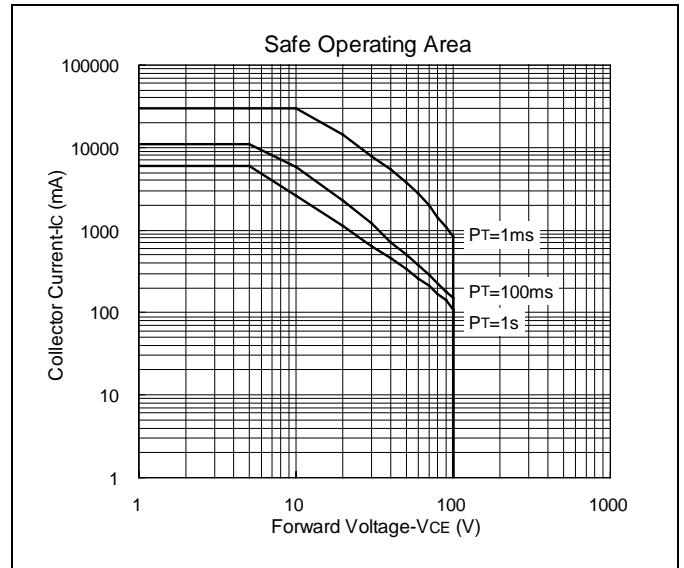
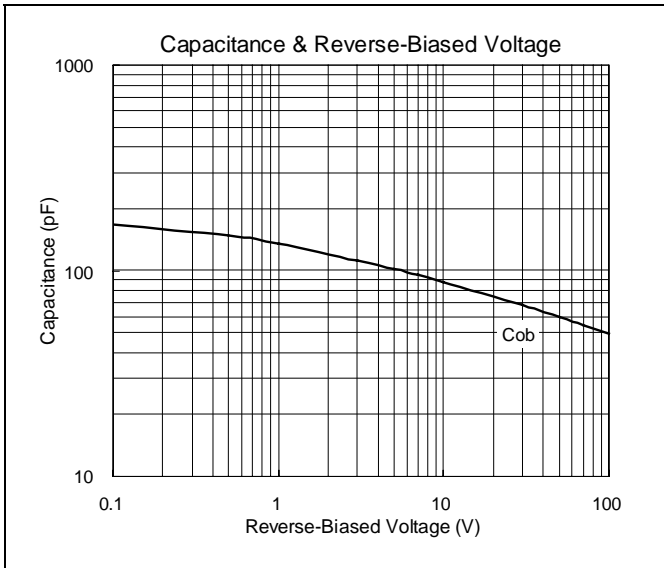
Darlington Schematic





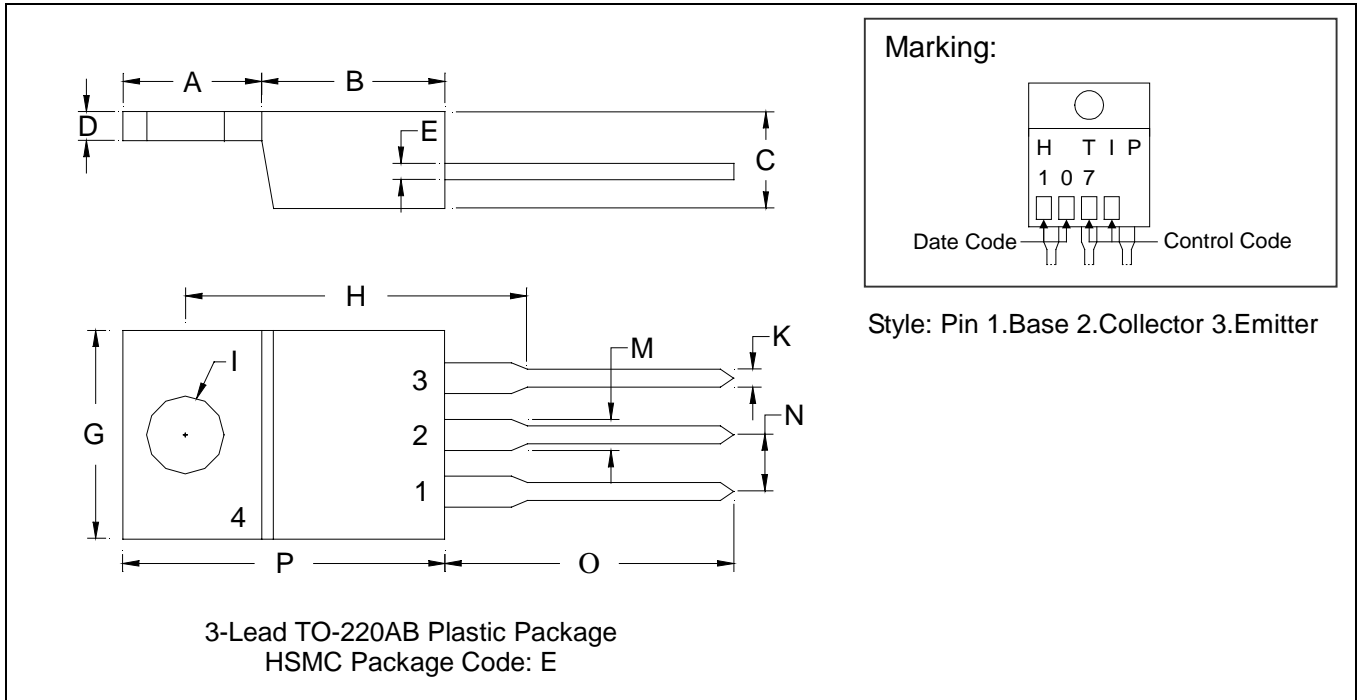
Characteristics Curve







TO-220AB Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
 - 2.Controlling dimension: millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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